



Material Content Data Sheet



Sales Product Name				ESD101-B1-02ELS E6327		Issued		25. September 2017	
MA#				MA001101872					
Package				PG-TSSLP-2-4		Weight*		0.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.33		3252		
	noble metal	gold	7440-57-5	0.003	1.26		12620		
	inorganic material	silicon	7440-21-3	0.020	9.35	10.94	93508	109380	
leadframe	non noble metal	nickel	7440-02-0	0.108	50.43	50.43	504275	504275	
wire	noble metal	gold	7440-57-5	0.004	1.83	1.83	18298	18298	
	encapsulation	organic material	carbon black	1333-86-4	0.000	0.16		1628	
	plastics	epoxy resin	-	0.010	4.72		47223		
		inorganic material	silicondioxide	60676-86-0	0.059	27.68	32.56	276834	325685
leadfinish	noble metal	gold	7440-57-5	0.004	1.72	1.72	17206	17206	
plating	noble metal	palladium	7440-05-3	0.001	0.60		5967		
		noble metal	gold	7440-57-5	0.004	1.92	2.52	19189	25156
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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